日本電子機械工業会規格
Standard of Electronic Industries Association of Japan

EIAJ ED-7311-10A

集積回路パッケージ個別規格
［P-BGA（キャビティダウンタイプ）］
Standards of integrated circuits package
［P-BGA(cavity down type)］

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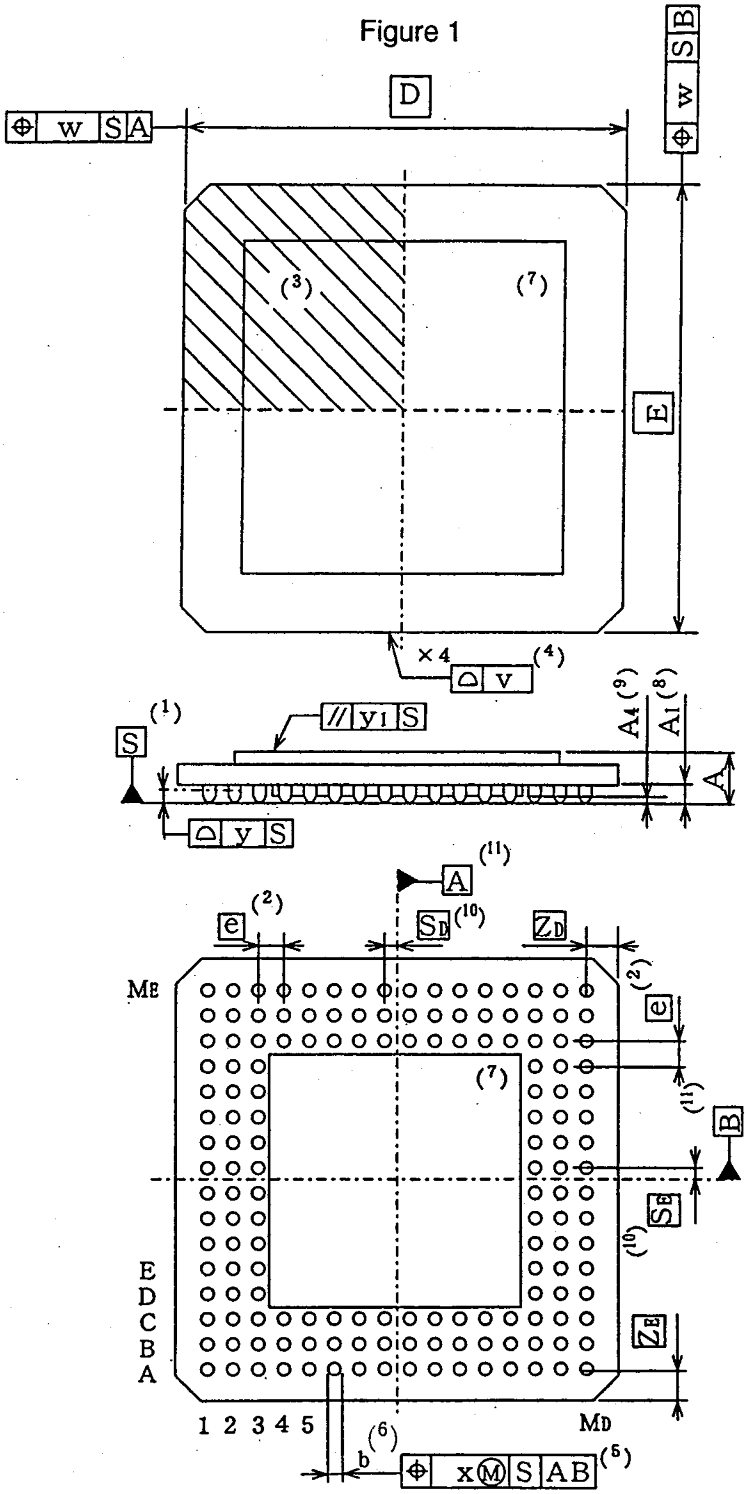
照合文字と図面
Reference symbol and schematics

図1

Figure 1



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